## DECLARATION FOR U.S. PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

the specification of which is attached hereto unless the following is checked:

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

METHOD OF FORMING NITRIDE-BASED SEMICONDUCTOR LAYER, AND METHOD OF MANUFACTURING NITRIDE-BASED SEMICONDUCTOR DEVICE

	was filed on Application Number (if applicable).		States Application Number or was amended on	PCT International
	e that I have reviewed claim(s), as amended by		the contents of the above-i	dentified specification
	e the duty to disclose in ral Regulations, § 1.56.	formation which	is material to the patentability	as defined in Title 37
application(s)	for patent or inventor's or patent or inventor's co	s certificate listed	, United States Code, \$119( below and have also identifi filing date before that of the	fied below any foreign
(List prior foreign applications. See note A on back of this page)		(Country) (Country)	O1/09/2000 (Day/Month/Year Filed) (Day/Month/Year Filed)	Priority Claimed           _X         Yes         _ No           _X         Yes         _ No            Yes         _ No
(See note B o	n back of this page)	See attached	list for additional prior foreig	n applications
I hereby clain application(s)		e 35, United State	es Code, § 119(e) of any Un	nited States provisional
	(Application I	Number)	(Filing Date)	
	(Application I	Number)	(Filing Date)	

I hereby claim the benefit under Title 35, United States Code, \$120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, \$112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, \$1.56 which became available between the filing date of the prior application and the national or PCT international filing date of the application:

(List Prior U.S. Applications)	(Appln. Serial No.)	(Filing Date)	(Status) (patented, pending, abandoned)
	(Appln. Serial No.)	(Filing Date)	(Status) (patented, pending, abandoned)

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the United States Code, \$1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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